TOSHIBA BIPOLAR LINEAR INTEGRATED CIRCUIT SILICON MONOLITHIC

TA8062S

DUAL HIGHSIDE DRIVER

The TA8062S is a 0.3A highside driver containing two circuits in one package.

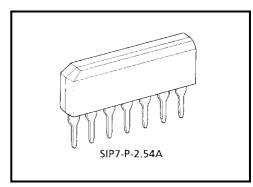
The input level is TTL compatible so that the output can be controlled directly from CPU system and the like. Protective functions are built in to protect IC and load from destruction caused of over stress.

FEATURES

- 2 circuit in one package.
- Output current capacity : 0.3A
- Protective function : Over-voltage Protection

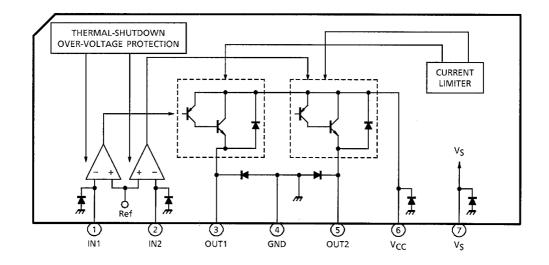
Current Limiter
Thermal-Shutdown

- Separated Power Supply of Power Portion and Logic portion.
- Built-in Counter Electromotive Force Absorption Diodes.
- SIP7pin Plastic Package.



Weight: 0.7 g (typ.)

BLOCK DIAGRAM AND PIN LAYOUT



PIN DESCRIPTION

PIN No.	SYMBOL	DESCRIPTION					
1	IN1	These terminals control output condition.					
2	IN2	The input level is TTL Compatible.					
3	OUT1	PNP-type complementary output pin with a current capacity of 0.3A. When the output supplied with a current exceeding the detection current (typically 0.55A) because of short-circuit, the output is limited to protect the IC.					
5	OUT2						
4	GND	Ground terminal					
6	V _{CC}	Power supply terminal for the output part of IC. Built-in over-voltage function protects IC and load when the supplied voltages higher than 30V.					
7	V _S	Power supply terminal for the control part of IC and this pin is separated from V _{CC}					

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Power Supply Voltage	V _{CC}	50 (1s)	V
Input Voltage	V _{IN}	-0.3~V _{CC} +0.3	V
Output Current	lout	300	mA
Power Dissipation	P _D	0.92	W
Operation Temperature	T _{opr}	− 40~85	°C
Storage Temperature	T _{stg}	-55~150	°C
Lead Temperature Time	T _{sol}	260 (10s)	°C

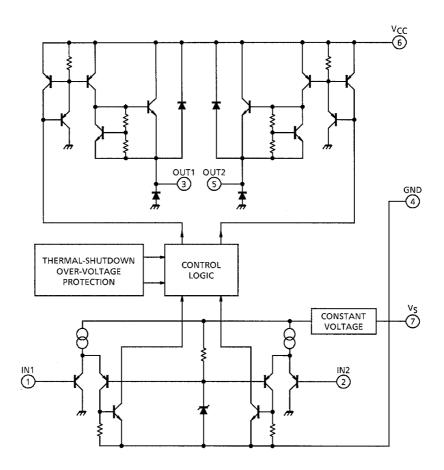
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ELECTRICAL CHARACTERISTICS (V_S, V_{CC} = $8\sim16$ V, Ta = $-40\sim85$ °C)

CHARACTERISTIC	SYMBOL	PIN	TEST CIR- CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT
	I _{S1}	Vs	_	(IN1, IN2) = (L, L)	_	2.5	6	mA
Power Supply Current (I)	I _{S2}		_	(IN1, IN2) = (L, H) or (H, L)	_	4	9.5	
	I _{S3}		_	(IN1, IN2) = (H, H)	_	4	9.5	
	I _{CC1}	V _{CC}	_	(IN1, IN2) = (L, L)	_	_	1	mA
Power Supply Current (II)	I _{CC2}		_	(IN1, IN2) = (L, H) or (H, L)	_	7.5	15	
	I _{CC3}		_	(IN1, IN2) = (H, H)	_	14	30	
Input Voltage	V _{IL}	IN1/ IN2	_		_	_	0.8	V
input voltage	V _{IH}				2.0	_	_	
Input Current	I _{IL}	IN1/ IN2	_	V _{IN} = 0.4V	-20	_	_	μΑ
Input Current	I _{IH}		_	V _{IN} = V _{CC}	_	_	10	
Output Saturation Voltage	V _{sat}	OUT1 / OUT2	_	I _{OUT} = 300mA	_	1.0	1.5	V
Output Leakage Current	I _{LEAK}	OUT1 / OUT2	_	V _{OUT} = 0V	-100	_	_	μΑ
Diode Forward Voltage	V _F	OUT1 / OUT2	_	I _F = 200mA	_	1.1	_	V
Output Limit Current	I _{SC}	OUT1 / OUT2	_		0.3	0.55	_	А
Object designs Territories	T _{SD-H}	OUT1 / OUT2	_	OUT = ON → OFF	_	150	_	°C
Shutdown Temperature	T _{SD-L}		_	OUT = OFF → ON	_	130	_	
Over-Voltage Detection	V _{SD}	V _{CC}	_		27	30	33	V
Transfer Dalay Time	t _{pLH}		_		_	1	10	- µs
Transfer Delay Time	t _{pHL}		_		_	1	10	

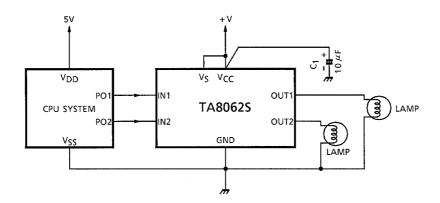
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EQUIVALENT CIRCUIT



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APPLICATION CIRCUIT



Cautions for wirings

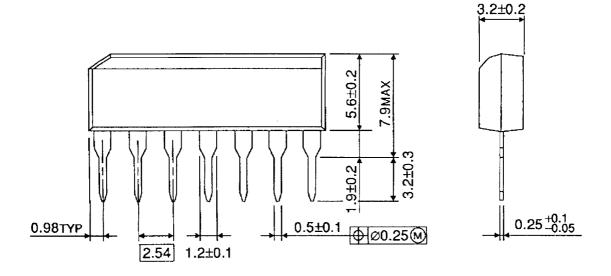
 C_1 is for absorbing disturbance, noise, etc.

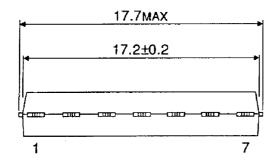
Connect it as close to the IC as possible.

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PACKAGE DIMENSIONS

SIP7-P-2.54A Unit: mm





Weight: 0.7g (Typ.)

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RESTRICTIONS ON PRODUCT USE

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